

In the Claims

Claims 1-10 (Canceled).

11 (Original). A device comprising:

a first structure having front and back sides;

a microelectromechanical system formed on said front side of said first structure;

a second structure bonded to said first structure by surface mount connection;

a cavity surrounding said system between said first and second structures; and

an open area in said first structure under said system.

12 (Original). The device of claim 11 including a cover over said back side of said first structure closing said open area.

13 (Original). The device of claim 12 wherein said cover is adhesively secured to said first structure.

14 (Original). The device of claim 12 wherein said cover includes a plastic film.

15 (Original). The device of claim 11 including a solder bump on one of said first and second structures surface mounted to the other of said first and second structures to form a hermetic cavity between said first and second structures.

16 (Original). The device of claim 11 wherein said system is a film bulk acoustic resonator.

17 (Original). The device of claim 11 wherein said system is a switch.

18 (Original). The system of claim 11 wherein said system is a transmission line.

19 (Original). The device of claim 11 wherein said second semiconductor structure is formed of glass.

20 (Original). The device of claim 19 including contacts which make an electrical connection to said system and extend through said second structure, said contacts including a surface mount bump.

21 (Original). A device comprising:

- a first semiconductor structure having front and back sides;
- a microelectromechanical system formed on said front side of said first structure;
- a second structure bonded to said first structure by a surface mount connection, said connection including a solder bump that defines a hermetic cavity between said first and second structures surrounding said system;
- an open area in said first structure under said system; and
- a film applied to the back side of said first semiconductor structure forming said open area between said first semiconductor structure and said film.

22 (Original). The device of claim 21 wherein said film is a plastic film.

23 (Original). The device of claim 22 wherein said film is adhesively secured to said back side.

24 (Original). The device of claim 21 wherein said first and second structures are semiconductor structures.

25 (Original). The device of claim 21 wherein said second structure is an insulator.

26 (Original). The device of claim 25 wherein said second structure is glass.

27 (Original). The device of claim 26 including an aperture through said second structure said aperture being filled by a solder bump that extends completing through said second structure.

28 (Original). The device of claim 21 wherein said system is a film bulk acoustic resonator.

29 (Original). The device of claim 21 wherein said system is a switch.

30 (Original). The system of claim 21 wherein said system is a transmission line.